



SEMICELL CAL-DIODE

SKCD 31 C 060 I3

$I_F = 50\text{ A}$

$V_{RRM} = 600\text{ V}$

Size: 5,6 mm X 5,6 mm

Package: wafer frame

Features

- 600V, 1200V and 1700V
- low forward voltage drop
- easy paralleling due to a small forward voltage spread
- low temperature dependence
- very soft recovery behavior
- small switching losses
- high ruggedness
- compatible to thick wire bonding
- compatible to all standard solder processes

Typical Applications

- freewheeling diode for IGBT
- optimal at frequencies > 8 kHz

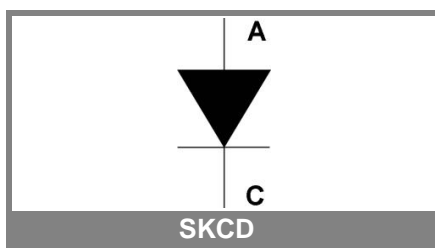
Absolute Maximum Ratings			
Symbol	Conditions	Values	Units
V_{RRM}	$T_{vj} = 25\text{ °C}, I_R = 0,1\text{ mA}$	600	V
$I_{F(AV)}$	$T_h = 80\text{ °C}, T_{vjmax} = 150\text{ °C}$	40	A
I_{FSM}	$T_{vj} = 25\text{ °C}, 10\text{ ms, half sine wave}$		A
	$T_{vjmax} = 150\text{ °C}, 10\text{ ms, half sine wave}$	440	A
T_{vjmax}		+ 150	°C

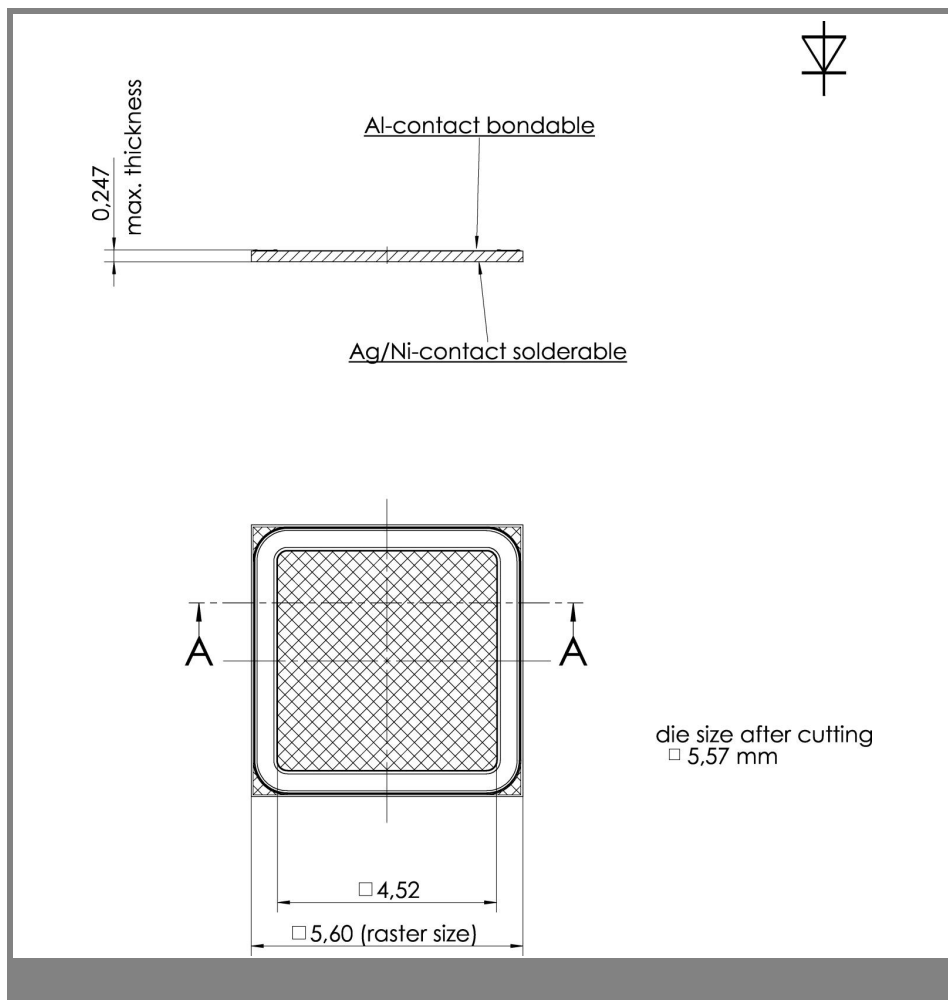
Electrical Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
I^2t	$T_{vjmax}, 10\text{ ms, half sine wave}$			970	A ² s
I_R	$T_{vj} = 25\text{ °C}, V_{RRM}$			0,1	mA
	$T_{vj} = 125\text{ °C}, V_{RRM}$			4	mA
V_F	$T_{vj} = 25\text{ °C}, I_F = 50\text{ A}$		1,35	1,6	V
	$T_{vj} = 125\text{ °C}, I_F = 50\text{ A}$		1,35	1,6	V
$V_{(TO)}$	$T_{vj} = 125\text{ °C}$		0,9		V
r_T	$T_{vj} = 125\text{ °C}$		8,3		mΩ

Dynamic Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
t_{rr}	$T_{vj} = 25\text{ °C}, 50\text{ A}, 300\text{ V}, 800\text{ A}/\mu\text{s}$				ns
	$T_{vj} = 125\text{ °C}, 50\text{ A}, 300\text{ V}, 800\text{ A}/\mu\text{s}$				ns
Q_{rr}	$T_{vj} = 25\text{ °C}, 50\text{ A}, 300\text{ V}, 800\text{ A}/\mu\text{s}$				μC
	$T_{vj} = 125\text{ °C}, 50\text{ A}, 300\text{ V}, 800\text{ A}/\mu\text{s}$		3,3		μC
I_{rrm}	$T_{vj} = 25\text{ °C}, 50\text{ A}, 300\text{ V}, 800\text{ A}/\mu\text{s}$				A
	$T_{vj} = 125\text{ °C}, 50\text{ A}, 300\text{ V}, 800\text{ A}/\mu\text{s}$		30		A

Thermal Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
T_{vj}		- 40		+ 150	°C
T_{stg}		- 40		+ 150	°C
T_{solder}	10 min			+ 250	°C
T_{solder}	5 min			+ 320	°C
$R_{th(j-h)}$	soldered on 0,38 mm DCB, reference point on copper heatsink close to the chip.		1		K / W

Mechanical Characteristics		
Parameter		Units
raster size	5,6 x 5,6	mm
Area total	31,36	mm ²
Chips / wafer	314	pcs
Anode metallisation	bondable (Al)	
Cathode metallisation	solderable (Ag / Ni)	
wire bond	Al, diameter ≤ 500 μm	





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